

ABSTRACT OF THE DISCLOSURE

5 A semiconductor processing apparatus detecting sticking of a wafer includes a stage on which a wafer is mounted, a wafer lift pin for separating the wafer from the stage, a control device controlling a vibrator power supply and control unit to vibrate a vibrator, controlling a detector to detect a state of vibration, and detecting presence/absence of sticking between the wafer and the stage based on the state of vibration prior to raising of the wafer with the wafer lift pin, and an alarm device outputting an alarm when the sticking occurs.